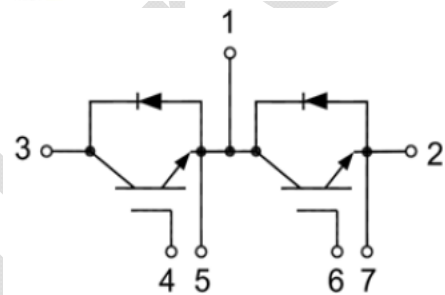


# GT100HF120T1H-M

## IGBT Module

### Features:

- Field Stop Trench Gate IGBT
- Short Circuit Rated >10 $\mu$ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested (2 $\times$ I<sub>c</sub>)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement



### Applications:

- Industrial Inverters
- Servo Applications
- EV And EHV
- Induction Heating
- UPS Systems

### IGBT, Inverter

#### Maximum Rated Values of IGBT (T<sub>C</sub>=25 $^{\circ}$ C unless otherwise specified)

V <sub>CES</sub>	Collector-Emitter Blocking Voltage		1200	V
V <sub>GES</sub>	Gate-Emitter Voltage		$\pm$ 20	V
I <sub>C</sub>	Continuous Collector Current	T <sub>C</sub> = 100 $^{\circ}$ C	100	A
		T <sub>C</sub> = 25 $^{\circ}$ C	200	A
I <sub>CM</sub>	Repetitive Peak Collector Current	T <sub>J</sub> = 175 $^{\circ}$ C	200	A
t <sub>SC</sub>	Short Circuit Withstand Time		>10	$\mu$ s
P <sub>D</sub>	Maximum Power Dissipation per IGBT	T <sub>C</sub> = 25 $^{\circ}$ C T <sub>Jmax</sub> = 175 $^{\circ}$ C	714	W

## Electrical Characteristics of IGBT ( $T_C=25^\circ\text{C}$ unless otherwise specified)

### Static Characteristics

Symbol	Description	Conditions	Min	Typ	Max	Unit
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=1\text{mA}, V_{CE}=V_{GE}$	5.0	5.5	6.6	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=100\text{A}, V_{GE}=15\text{V}$	$T_J=25^\circ\text{C}$	1.70	2.00	V
			$T_J=125^\circ\text{C}$	1.90		V
			$T_J=150^\circ\text{C}$	1.90		V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}, V_{CE}=V_{CES}, T_J=25^\circ\text{C}$			1	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}, V_{CE}=0\text{V}, T_J=25^\circ\text{C}$			200	nA
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		8.03		nF
$C_{oes}$	Output Capacitance					nF
$C_{res}$	Reveres Transfer Capacitance			0.59		nF

### Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600\text{V}, I_C=100\text{A}, R_{Gon}=1\Omega, V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	228		ns
			$T_J=125^\circ\text{C}$	250		
			$T_J=150^\circ\text{C}$	254		
$t_r$	Rise Time		$T_J=25^\circ\text{C}$	63		ns
			$T_J=125^\circ\text{C}$	67		
			$T_J=150^\circ\text{C}$	69		
$t_{d(off)}$	Turn-off Delay Time		$T_J=25^\circ\text{C}$	269		ns
			$T_J=125^\circ\text{C}$	279		
			$T_J=150^\circ\text{C}$	284		
$t_f$	Fall Time	$T_J=25^\circ\text{C}$	184		ns	
		$T_J=125^\circ\text{C}$	291			
		$T_J=150^\circ\text{C}$	317			
$E_{on}$	Turn-on Switching Loss	$V_{CC}=600\text{V}, I_C=100\text{A}, R_{Gon}=1\Omega, V_{GE}=\pm 15\text{V},$ $di/dt=1387\text{A}/\mu\text{s}(T_J=150^\circ\text{C}),$ Inductive Load	$T_J=25^\circ\text{C}$	3.1		mJ
		$T_J=125^\circ\text{C}$	4.3			
		$T_J=150^\circ\text{C}$	4.8			

E <sub>off</sub>	Turn-off Switching Loss	V <sub>CC</sub> =600V, I <sub>C</sub> =100A, R <sub>Goff</sub> =1Ω, V <sub>GE</sub> =±15V, du/dt=4448V/μs(T <sub>J</sub> =150°C), Inductive Load	T <sub>J</sub> =25°C	5.28	mJ
			T <sub>J</sub> =125°C	8.33	
			T <sub>J</sub> =150°C	9.30	
Q <sub>g</sub>	Total Gate Charge	V <sub>GE</sub> =+15V...-15V	T <sub>J</sub> =25°C	745	nC
R <sub>g internal</sub>	Internal Gate Resistance		T <sub>J</sub> =25°C	7.5	Ω
RBSOA	I <sub>C</sub> =200A, V <sub>CC</sub> =1050V, V <sub>p</sub> =1200V, R <sub>Goff</sub> =1Ω, V <sub>GE</sub> =+15V to 0V, T <sub>J</sub> =150°C			Trapezoid	
SC data	V <sub>CC</sub> =600V, t <sub>p</sub> =10us, V <sub>ge</sub> =+/-15V, R <sub>Gon</sub> =1ohm, R <sub>Goff</sub> =1ohm, T <sub>J</sub> =25°C			575	A
R <sub>θJC</sub>	IGBT Thermal Resistance: Junction-To-Case			0.21	°C/W

### Diode, Inverter

#### Maximum Rated Values (T<sub>C</sub> = 25°C unless otherwise specified)

V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	1200	V
I <sub>F</sub>	Diode Continuous Forward Current	100	A
I <sub>FM</sub>	Peak FWD Current Repetitive	200	A

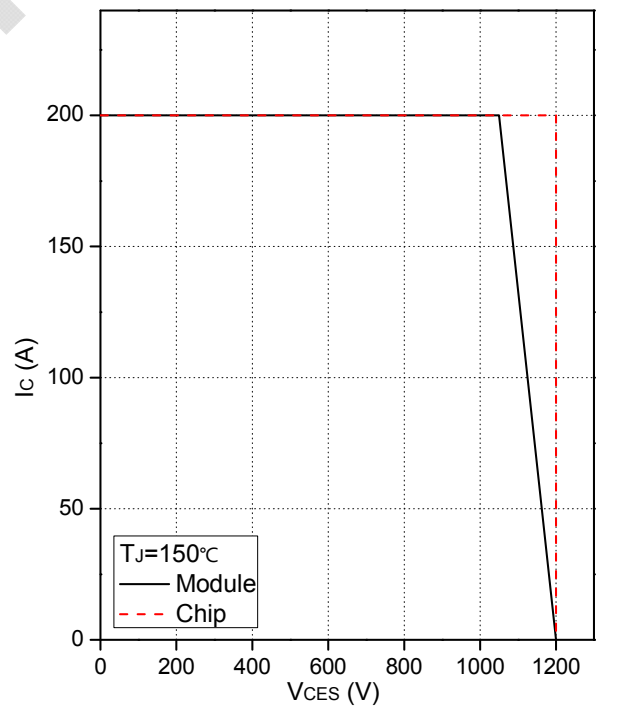
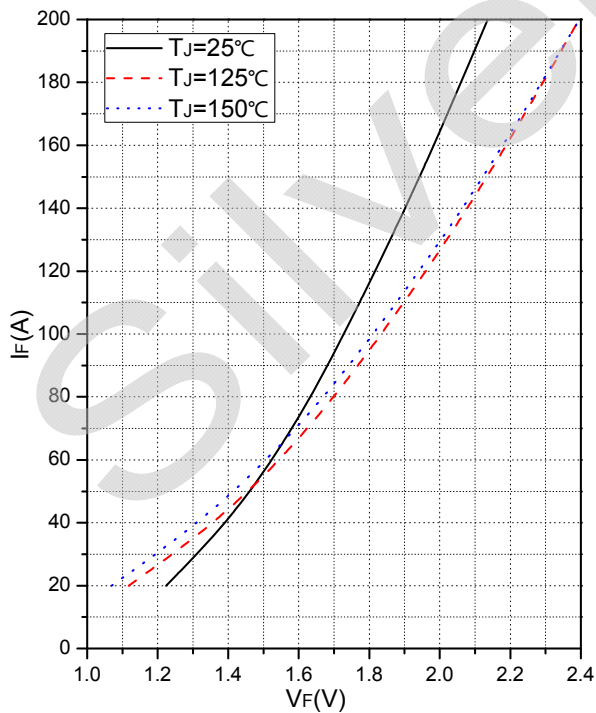
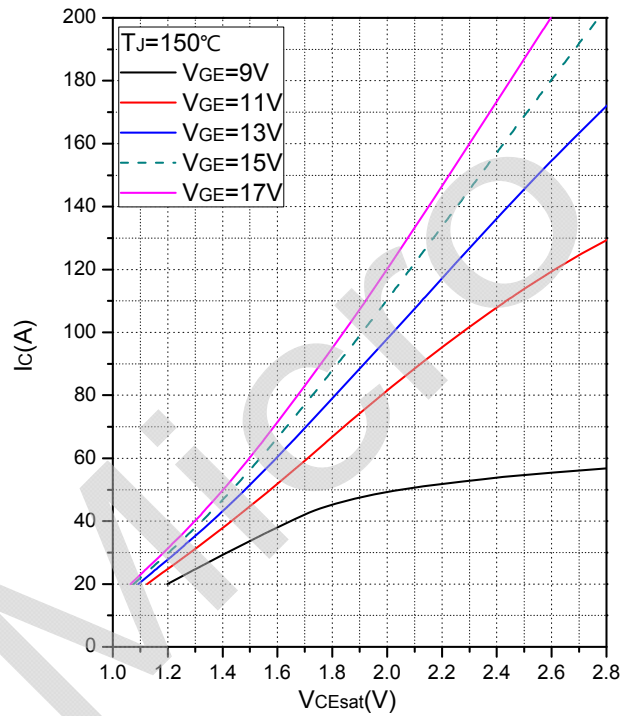
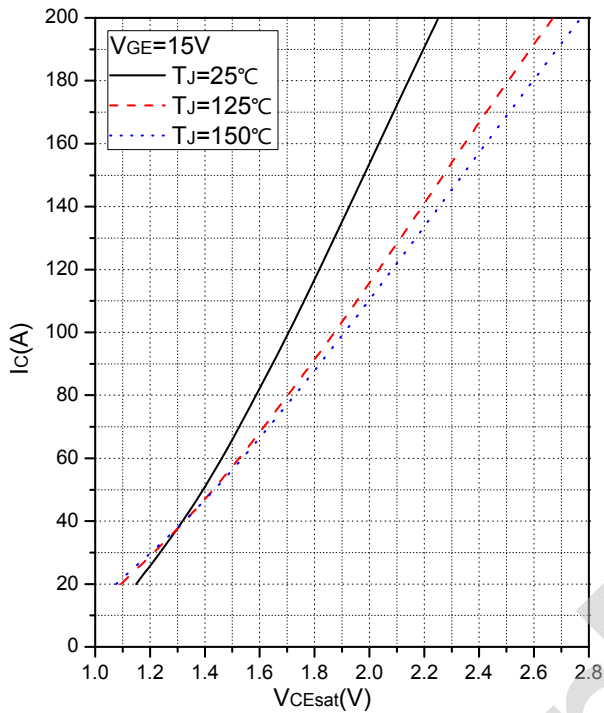
#### Electrical Characteristics of FWD (T<sub>C</sub>=25°C unless otherwise specified)

Symbol	Description	Conditions	Min	Typ	Max	Unit
V <sub>FM</sub>	Forward Voltage	I <sub>F</sub> =100A	T <sub>J</sub> =25°C	1.70		V
			T <sub>J</sub> =125°C	1.80		
			T <sub>J</sub> =150°C	1.80		
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =100A, -diF/dt =1911A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	260		ns
			T <sub>J</sub> =125°C	396		
			T <sub>J</sub> =150°C	454		
I <sub>rr</sub>	Peak Reverse Recovery Current	V <sub>R</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	92		A
			T <sub>J</sub> =125°C	104		
			T <sub>J</sub> =150°C	105		

Q <sub>rr</sub>	Reverse Recovery Charge		T <sub>J</sub> =25°C	10.2	μC
			T <sub>J</sub> =125°C	16.8	
			T <sub>J</sub> =150°C	19.2	
E <sub>rec</sub>	Reverse Recovery Energy	I <sub>F</sub> =100A, -diF/dt =1911A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	4.83	mJ
			T <sub>J</sub> =125°C	7.92	
			T <sub>J</sub> =150°C	9.13	
R <sub>θJC</sub>	Diode Thermal Resistance: Junction-To-Case			0.34	°C/W

## Module

Symbol	Description		Min	Typ	Max	Unit
V <sub>iso</sub>	Isolation Voltage (All Terminals Shorted)	f = 50Hz, 1minute	2500			V
Internal Isolation			Al2O3			
Material of Module Baseplate			Copper			
d <sub>creep</sub>	Creepage Distance: Terminal to Heatsink			17.0		mm
	Creepage Distance: Terminal to Terminal			20.0		mm
d <sub>clear</sub>	Clearance: Terminal to Heatsink			17.0		mm
	Clearance: Terminal to Terminal			9.5		mm
L <sub>SCE</sub>	Stray Inductance Module			30		nH
T <sub>J</sub>	Maximum Junction Temperature				175	°C
T <sub>JOP</sub>	Maximum Operating Junction Temperature Range		-40		+150	°C
T <sub>stg</sub>	Storage Temperature		-40		+125	°C
CTI	Comparative Tracking Index		200			
R <sub>θCS</sub>	Case-To-Sink Thermally (Conductive Grease Applied)			0.1		°C/W
T	Power Terminals Screw:M5		3.0		5.0	N·m
T	Mounting Screw:M6		4.0		6.0	N·m
G	Weight			135		g



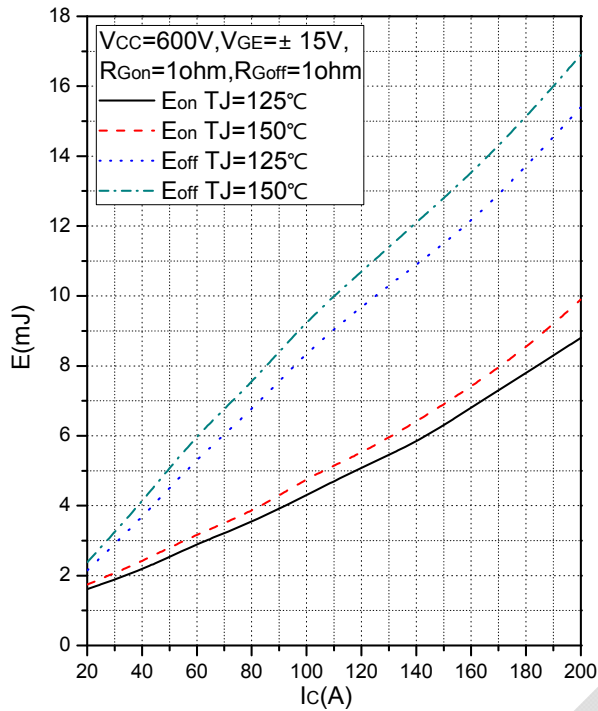


Fig.5 Typical Switching Loss vs. Collector Current

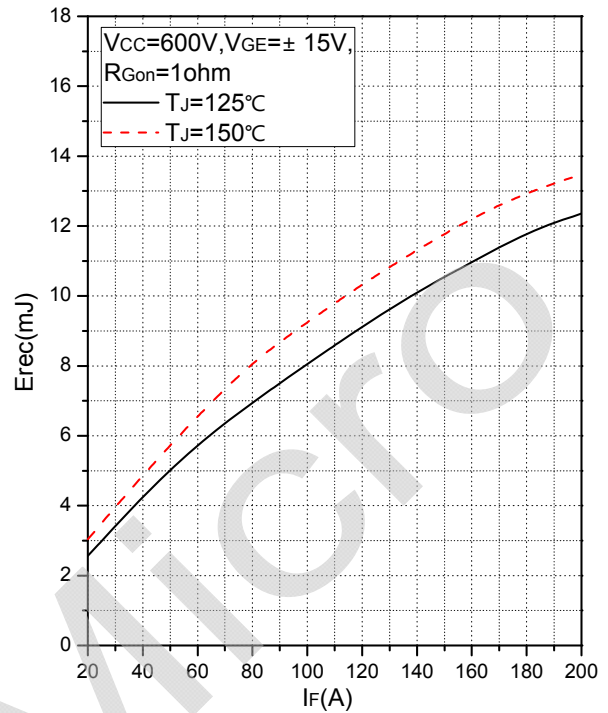


Fig.6 Typical Switching Loss vs. Forward Current

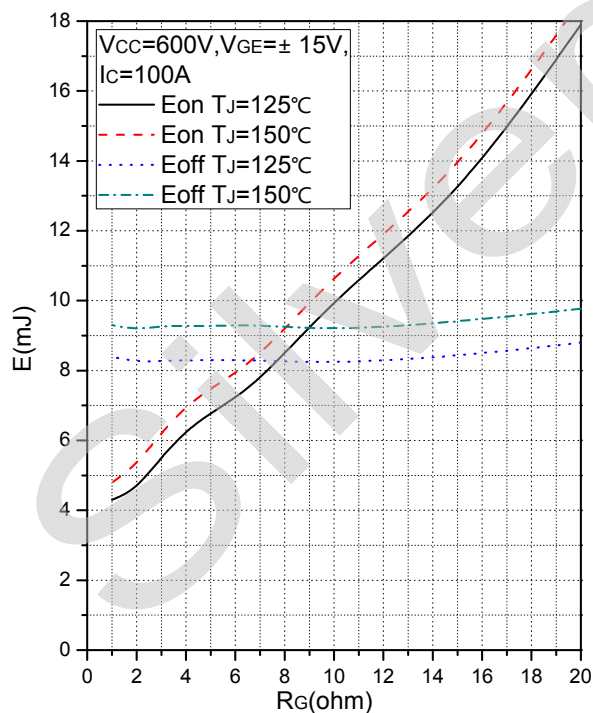


Fig.7 Typical Switching Loss vs. Gate Resistance

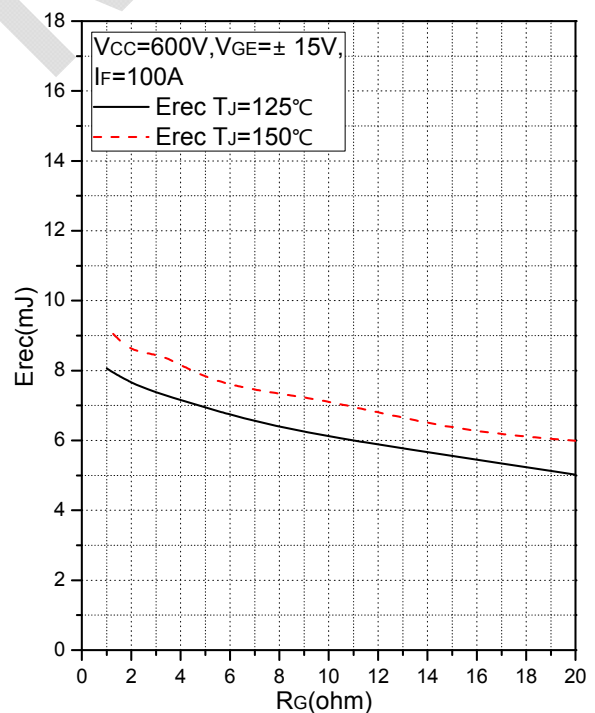


Fig.8 Typical Switching Loss vs. Gate Resistance

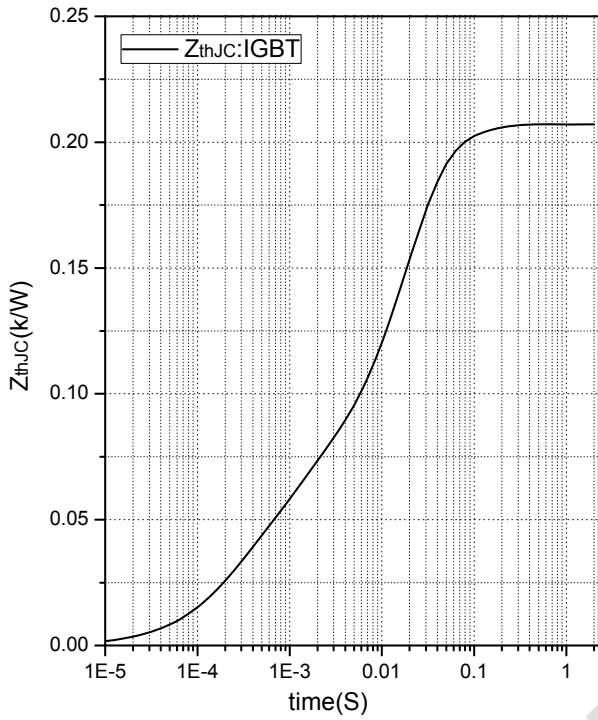


Fig.9 Transient Thermal Impedance

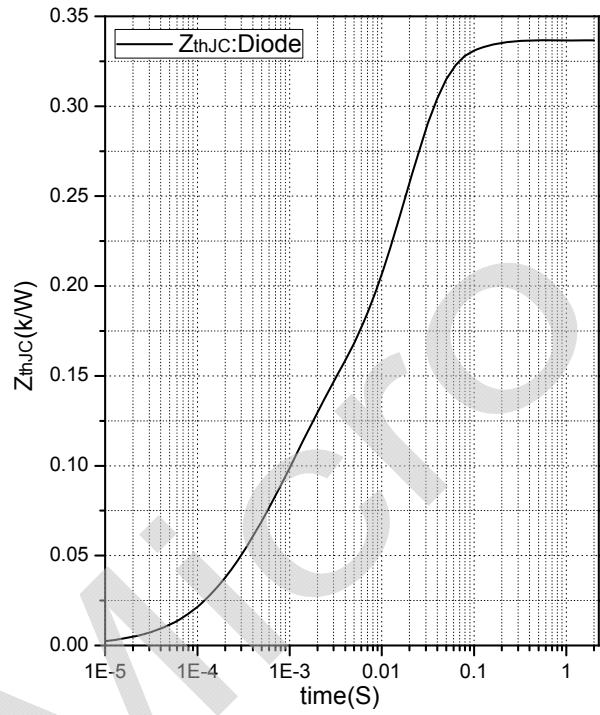


Fig.10 Transient Thermal Impedance

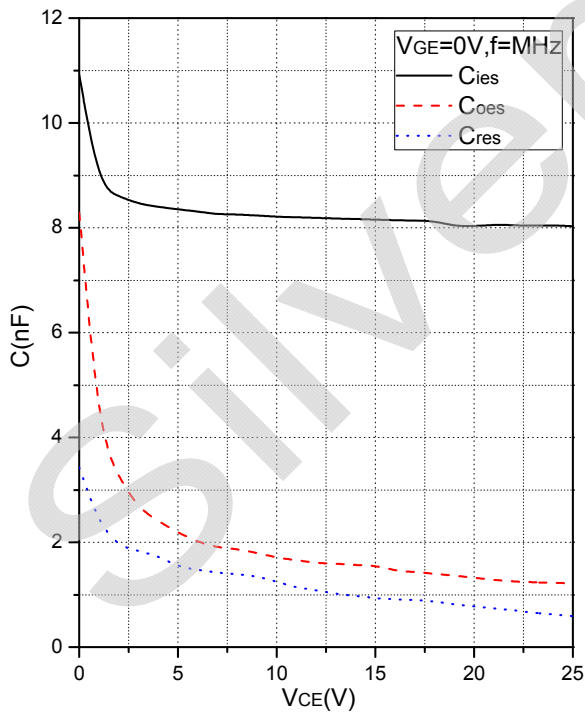
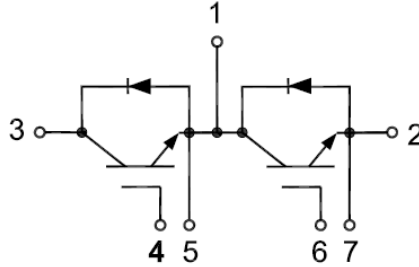
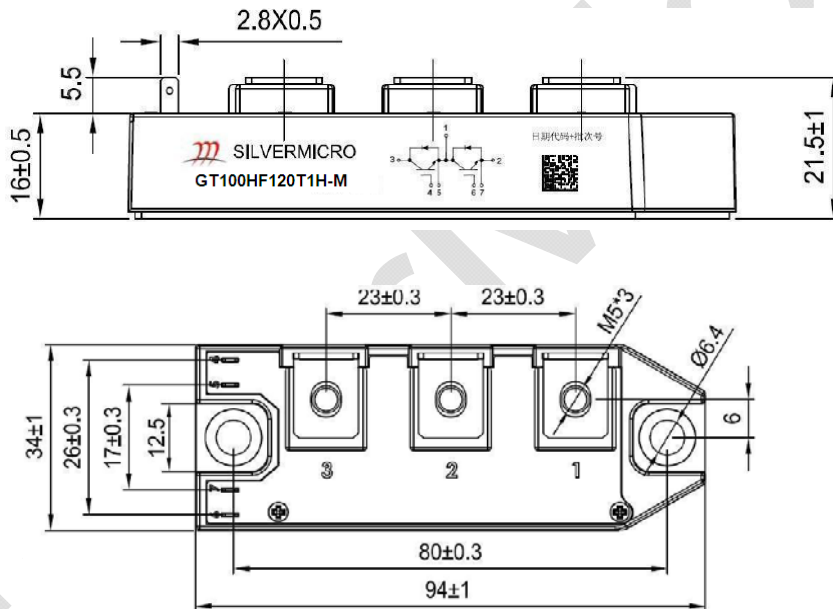


Fig.11 Capacitance Characteristics

### Internal Circuit



### Package Outline (Unit: mm):







Date	Revision	Notes
04/17/2020	A	Final Version

## Announcements

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